

# STSW-BT3.0DP2

## STBT3.0DP2 Bluetooth® v3.0 firmware package release

Data brief

Application			
Data Package with AT Command			
Bluetooth Profiles			
SPP DID HID iAP2			
Bluetooth Stack			
RFCOMM SDP			
L2CAP			
HCI			
Operating System			
STM32 Hardware Abstraction Layer			
SPBT3ODPx firmware			
Bluetooth Controller			
Link Manager			
Baseband			
Radio			

### **Features**

- SPP profile for serial cable replacement client and server
- iAP2 profile allowing communication with Apple®iOS Bluetooth-enabled devices
- HID profile for keyboard and mouse devices
- Deep sleep mode with wake up from host CPU or from Bluetooth radio
- Command and bypass modes during active connection. Switch between modes via AT commands over UART or via GPIOs
- Auto-reconnect, auto-sniff
- Remote control mode
- Configurable bonding security level
- User configuration stored in nonvolatile memory

### Description

The package contains a SIG certified Bluetooth<sup>®</sup> 3.0 stack controlled via AT commands over SPBT3.0DP2 UART interface.

SPBT3.0DP2 modules come pre-programmed with a production-ready firmware image, the version of which may change at any time without notice. The software version of the preloaded stack image can be retrieved through a specific API command (see corresponding user manual).

Any firmware upgrades will be made available free-of-charge to end users through www.st.com.

#### **Revision history** 1

Table 1: Document revision history

Date	Version	Changes
01-Mar-2017	1	Initial release.



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